

IN THE CLAIMS:

Please note that all claims currently pending and under consideration in the referenced application are shown below. Please enter these claims as amended. This listing of claims will replace all prior versions and listings of claims in the application.

Please amend claim 19 as set forth below.

Listing of Claims:

1-18. (Withdrawn)

19. (Currently Amended) A method of fabricating a multi-die assembly, comprising:
providing a substrate including a plurality of conductors;
attaching at least one active face-down base die to said substrate in electrical communication
with at least some of said plurality of conductors;
providing a layer of conductive epoxy adhesive to a back side of the at least one base die;
placing a back side of at least one active face-up stack die one on the layer of conductive epoxy
adhesive;
curing the layer of conductive epoxy adhesive and securing the back side of at least one stack die
to said at least one base die;
~~electrically connecting~~ providing a direct electrical path between said at least one stack die
~~directly to~~ and at least one of said plurality of conductors; and
electrically grounding said at least one base die via said layer of electrically conductive epoxy
adhesive and said at least one stack die.

20. (Canceled)

21. (Previously Amended) The method of claim 19, further comprising:
securing at least one discrete component to at least one of said at least one stack die, said at least
one base die, and said substrate;

electrically connecting said at least one discrete component to at least one of said stack die, said base die, and said substrate; and extending a die-to-component bond wire between said at least one stack die and said at least one discrete component.

22. (Previously Amended) The method of claim 21, further comprising: extending a component-to-substrate bond wire between said at least one discrete component and at least one of said plurality of substrate conductors.

23. (Previously Amended) The method of claim 19, further comprising: securing at least another stack die to said assembly; and electrically connecting said at least another stack die and at least one of said plurality of substrate conductors.

24. (Canceled)

25. (Previously Amended) The method of claim 23, further comprising securing said at least another stack die to said at least one stack die.

26. (Previously Amended) The method of claim 25, further comprising: securing at least one discrete component to said at least one stack die; and extending a die-to-component bond wire between said at least another stack die and said at least one discrete component.

27. (Previously Amended) The method of claim 25, further comprising: securing at least one discrete component to said at least one stack die; and extending a component-to-substrate bond wire between said at least one discrete component and at least one of said plurality of substrate conductors.

28. (Previously Amended) The method of claim 25, further comprising:
securing at least one discrete component to said at least one base die; and
extending a die-to-component bond wire between said at least another stack die and said at least
one discrete component.

29. (Previously Amended) The method of claim 25, further comprising:
securing at least one discrete component to said at least one base die; and
extending a component-to-substrate bond wire between said at least one discrete component and
at least one of said plurality of substrate conductors.

30. (Previously Amended) The method of claim 19, wherein the attaching at least one
active face-down base die includes attaching at least two active face-down base die to said
substrate and electrically coupling each of said at least two base die with at least one of said
plurality of substrate conductors.

31. (Previously Amended) The method of claim 30, further comprising bridging said
at least one stack die between said at least two base die.

32. (Previously Amended) The method of claim 31, further comprising securing at
least another stack die over said at least one stack die.

33. (Previously Amended) The method of claim 19, further comprising:
securing at least one discrete component to said substrate; and
extending a die-to-component bond wire between said at least one stack die and said at least one
discrete component.

34. (Previously Amended) The method of claim 33, further comprising
extending a die-to-component bond wire between said at least one discrete component and at
least one of said plurality of substrate conductors.